

KMM491000/KMM591000



1M x 9 DRAM SIP and SIMM Memory Modules

GENERAL DESCRIPTION

The Samsung KMM491000 and KMM591000 are 1M x 9 dynamic RAM high density memory modules. The ninth bit is generally used for parity and is controlled by $\overline{\text{CAS9}}$. Samsung's 1M x 9 memory modules consist of nine KM41C1000 DRAMS in 20-pin SOJ packages mounted on a 30 pin glass-epoxy substrate. A 0.22 μ F decoupling capacitor is mounted under each DRAM.

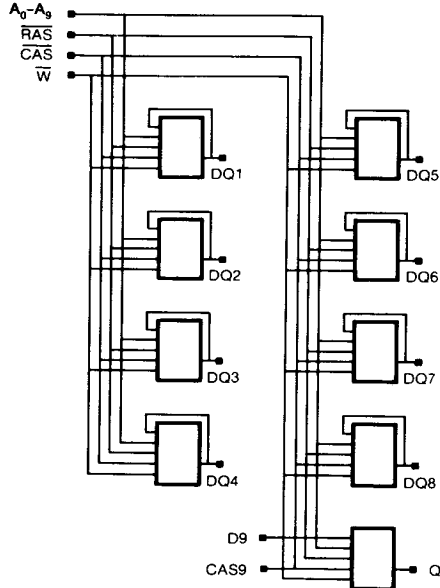
The 1M x 9 DRAM modules are available in two package styles. The KMM491000 is a SIP with leads suitable for through hole mounting or for mounting in a socket. The KMM591000 is a SIMM with edge connections and are intended for mounting into 30 pin edge connector sockets.

FEATURES

- 1,048,576 x 9-bit Organization
- Ninth device has separate D, Q and $\overline{\text{CAS}}$ for Parity applications.
- Performance range:

	t_{RAC}	t_{CAC}	t_{RC}
KMM491000-10	100ns	25ns	190ns
KMM591000-10	100ns	25ns	190ns
KMM491000-12	120ns	30ns	220ns
KMM591000-12	120ns	30ns	220ns
- Page Mode capability
- $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Refresh capability
- $\overline{\text{RAS}}$ -only and Hidden Refresh capability
- TTL compatible inputs and outputs
- Single +5V \pm 10% power supply
- 512 cycles/8ms refresh

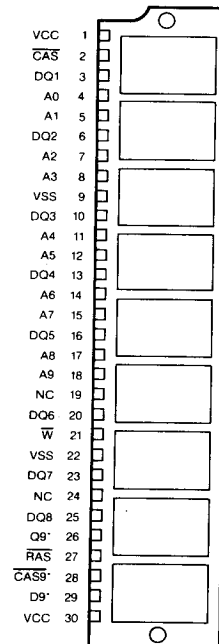
FUNCTIONAL BLOCK DIAGRAM



Part Numbers

KMM491000-10	100ns	SIP	Page Mode
KMM491000-12	120ns	SIP	Page Mode
KMM591000-10	100ns	SIMM	Page Mode
KMM591000-12	120ns	SIMM	Page Mode

PIN CONFIGURATION



Pin Name	Pin Function
A ₀ -A ₉	Address Input
D9	Data In
Q9	Data Out
DQ	Data In/Out
W	Read/Write Input
RAS	Row Address Strobe
CAS	Column Address Strobe
CAS9	Column Address Strobe
V _{CC}	Power (+5V)
V _{SS}	Ground

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ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS*

Item	Symbol	Rating	Unit
Voltage on any pin relative to V_{SS}	V_{IN}, V_{OUT}	-1 to +7.0	V
Voltage on V_{CC} supply relative to V_{SS}	V_{CC}	-1 to +7.0	V
Storage Temperature	T_{stg}	-55 to +150	°C
Power Dissipation	P_D	5.4	W
Short Circuit Output Current	I_{OS}	50	mA

*Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may effect device reliability.

RECOMMENDED OPERATING CONDITIONS (Voltages referenced to V_{SS} , $T_A = 0$ to 70°C)

Item	Symbol	Min	Typ	Max	Unit
Supply Voltage	V_{CC}	4.5	5.0	5.5	V
Ground	V_{SS}	0	0	0	V
Input High Voltage	V_{IH}	2.4	—	6.5	V
Input Low Voltage	V_{IL}	-1.0	—	0.8	V

DC AND OPERATING CHARACTERISTICS

(Recommended operating conditions unless otherwise noted.)

Parameter		Symbol	Min	Max	Unit
Operating Current* (RAS and CAS cycling @ $t_{RC} = \text{min.}$)	KMM491000-10, KMM591000-10 KMM491000-12, KMM591000-12	I_{CC1}	—	540 450	mA mA
Standby Current (RAS = CAS = V_{IH})		I_{CC2}	—	18	mA
RAS-Only Refresh Current* (CAS = V_{IH} , RAS cycling @ $t_{RC} = \text{min.}$)	KMM491000-10, KMM591000-10 KMM491000-12, KMM591000-12	I_{CC3}	—	540 450	mA mA
Fast Page Mode Current* (RAS = V_{IL} , CAS cycling: $t_{PC} = \text{min.}$)	KMM491000-10, KMM591000-10 KMM491000-12, KMM591000-12	I_{CC4}	—	360 270	mA mA
Standby Current (RAS = CAS = $V_{CC} - 0.2V$)		I_{CC5}	—	9	mA
CAS-Before-RAS Refresh Current* (RAS and CAS cycling @ $t_{RC} = \text{min.}$)	KMM491000-10, KMM591000-10 KMM491000-12, KMM591000-12	I_{CC7}	—	540 450	mA mA
Input Leakage Current (Any input $0 \leq V_{IN} \leq 6.5V$, all other pins not under test = 0 volts.)		I_{IL}	-90	90	μA
Output Leakage Current (Data out is disabled, $0V \leq V_{OUT} \leq 5.5V$)		I_{OL}	-10	10	μA
Output High Voltage Level ($I_{OH} = 5mA$)		V_{OH}	2.4	—	V
Output Low Voltage Level ($I_{OL} = 4.2mA$)		V_{OL}	—	0.4	V

*NOTE: I_{CC1} , I_{CC3} , I_{CC4} , I_{CC5} , and I_{CC7} are dependent on output loading and cycle rates. Specified values are obtained with the output open. I_{CC} is specified as an average current.

CAPACITANCE ($T_A = 25^\circ\text{C}$)

Item	Symbol	Min	Max	Unit
Input Capacitance ($A_0 - A_9$, W, CAS, RAS)	C_{IN1}	—	60	pF
Input Capacitance (D_9 , CAS ₉)	C_{IN2}	—	7	pF
Input Capacitance ($DQ_1 - DQ_8$)	C_{DO}	—	15	pF
Output Capacitance (Q_9)	C_{O9}	—	10	pF

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AC CHARACTERISTICS

(0°C ≤ T_A ≤ 70°C, V_{CC} = 5.0V ± 10%, see notes 1,2)

	Symbol	KMM491000-10 KMM591000-10		KMM491000-12 KMM591000-12		Unit	Notes
		Min	Max	Min	Max		
Standard Operation							
Random read or write cycle time	t _{RC}	190		220		ns	
Access time from $\overline{\text{RAS}}$	t _{RAC}		100		120	ns	3,4
Access time from $\overline{\text{CAS}}$	t _{CAC}		25		30	ns	4,4
Access time from column address	t _{AA}		50		60	ns	3,10
Access time from $\overline{\text{CAS}}$ precharge	t _{CPA}		55		65	ns	3
$\overline{\text{CAS}}$ to output in Low-Z	t _{CLZ}	5		5		ns	3
Output buffer turn-off delay	t _{OFF}	0	30	0	35	ns	6
Transition time (rise and fall)	t _T	3	50	3	50	ns	2
RAS precharge time	t _{RP}	80		90		ns	
RAS pulse width	t _{RAS}	100	10,000	120	10,000	ns	
RAS hold time	t _{RSH}	25		30		ns	
$\overline{\text{CAS}}$ precharge time	t _{CPN}	15		20		ns	
$\overline{\text{CAS}}$ hold time	t _{CSH}	100		120		ns	
$\overline{\text{CAS}}$ pulse width	t _{CAS}	25	10,000	30	10,000	ns	
RAS to $\overline{\text{CAS}}$ delay time	t _{RCD}	25	75	25	90	ns	4,5
RAS to column address delay time	t _{RAD}	20	50	20	60	ns	10
$\overline{\text{CAS}}$ to RAS precharge time	t _{CRP}	10		10		ns	
Row address set-up time	t _{ASR}	0		0		ns	
Row address hold time	t _{RAH}	15		15		ns	
Column address set-up time	t _{ASC}	0		0		ns	
Column address hold time	t _{CAH}	20		25		ns	
Column address hold time referenced to RAS	t _{AR}	95		115		ns	
Column address to RAS lead time	t _{RAL}	50		60		ns	
Read command set-up time	t _{RCS}	0		0		ns	
Read command hold time referenced to $\overline{\text{CAS}}$	t _{RCH}	0		0		ns	8
Read command hold time referenced to RAS	t _{RRH}	0		0		ns	8
Write command hold time	t _{WCH}	20		25		ns	
Write command hold time referenced to RAS	t _{WCR}	95		115		ns	
Write command pulse width	t _{WP}	20		25		ns	
Write command to RAS lead time	t _{RWL}	25		30		ns	
Write command to $\overline{\text{CAS}}$ lead time	t _{CWL}	25		30		ns	
Data-in set-up time	t _{DS}	0		0		ns	9
Data-in hold time	t _{DH}	20		25		ns	9
Data-in hold time referenced to RAS	t _{DHR}	95		115		ns	
Refresh period (512 cycles)	t _{REF}		8		8	ms	
Write command set-up time	t _{WCS}	0		0		ns	7
$\overline{\text{CAS}}$ to write enable delay	t _{CWD}	25		30		ns	7
CAS setup time (CAS-before-RAS refresh)	t _{CSR}	10		10		ns	
CAS hold time (CAS-before-RAS refresh)	t _{CHR}	30		30		ns	

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AC CHARACTERISTICS (Continued)

	Symbol	KMM491000-10 KMM591000-10		KMM491000-12 KMM591000-12		Unit	Notes
		Min	Max	Min	Max		
RAS precharge to CAS hold time	t_{RPC}	10		10		ns	
Refresh counter test CAS precharge time	t_{CPT}	50		60		ns	
Fast page mode cycle time	t_{PC}	60		70		ns	
CAS precharge time (Fast page mode)	t_{CP}	10		15		ns	
RAS pulse width (Fast page mode)	t_{RASP}	100	100,000	120	100,000	ns	

Notes:

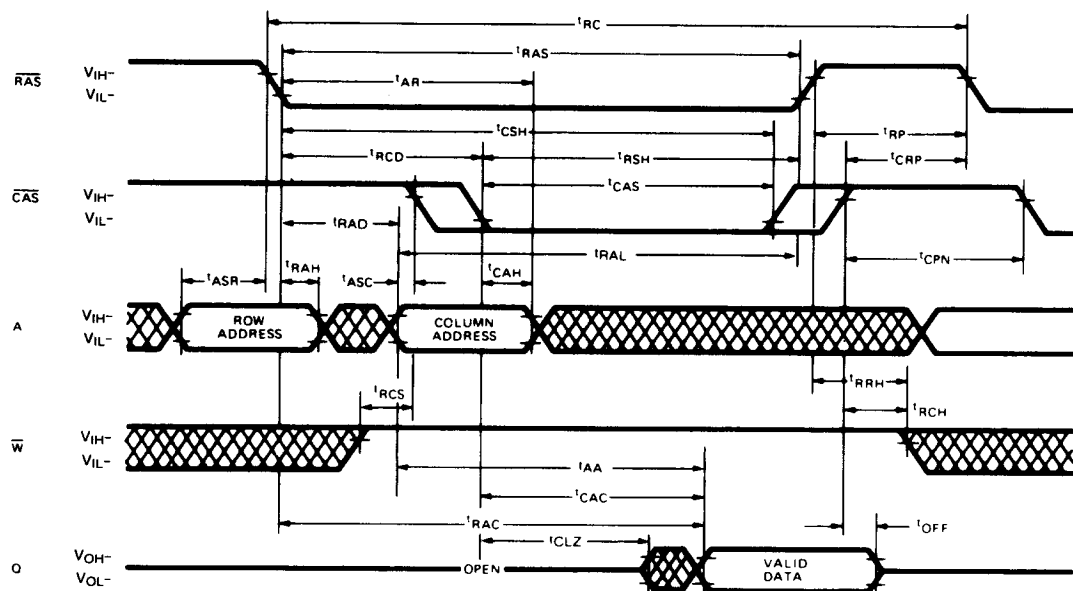
1. An initial pause of 200 μ s is required after power-up followed by any 8 RAS cycles before proper device operation is achieved.
2. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} (min) and V_{IL} (max) and are assumed to be 5ns for all inputs.
3. Measured with a load equivalent to 2 TTL loads and 100pF.
4. Operation within the t_{RCD} (max) limit insures that t_{RAC} (max) can be met. t_{RCD} (max) is specified as a reference point only. If t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC} .
5. Assumes that $t_{RCD} \geq t_{RCD}$ (max).
6. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL} .
7. t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are non restrictive operating parameters. They are included in the data sheet as electrical characteristic only. If $t_{WCS} \geq t_{WCS}$ (min) the cycle is an early write cycle and the data output pin will remain high impedance for the duration of the cycle.
8. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
9. These parameters are referenced to the CAS leading edge in early write cycles.
10. Operation within the t_{RAD} (max) limit insures that t_{RCD} (max) can be met. t_{RAD} (max) is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled by t_{AA} .

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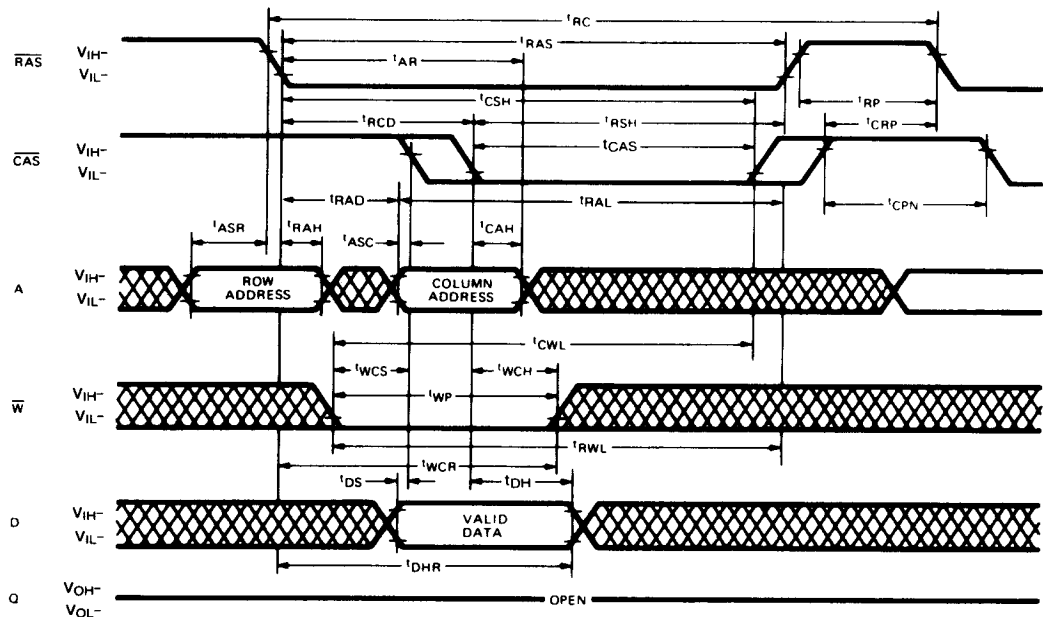
1M × 9 DRAM SIP and SIMM Memory Modules

TIMING DIAGRAMS

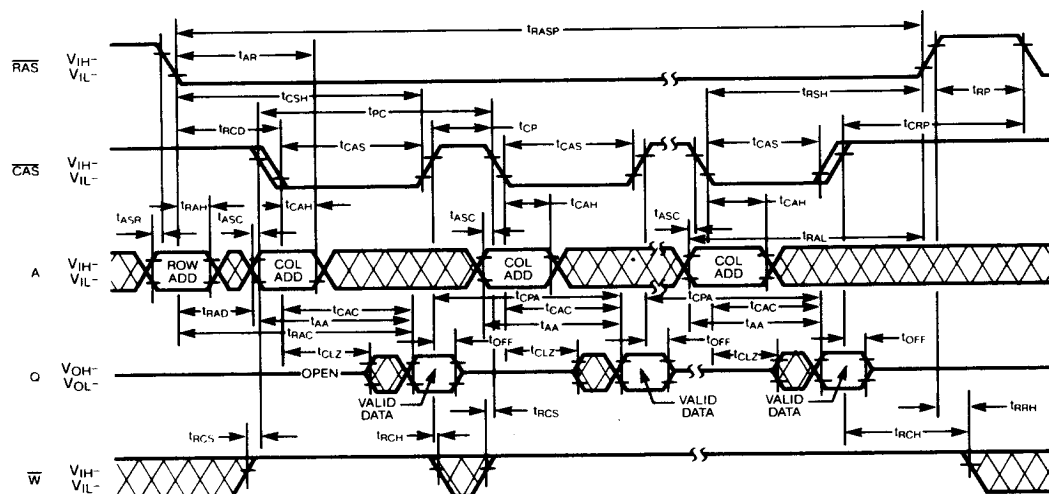
READ CYCLE



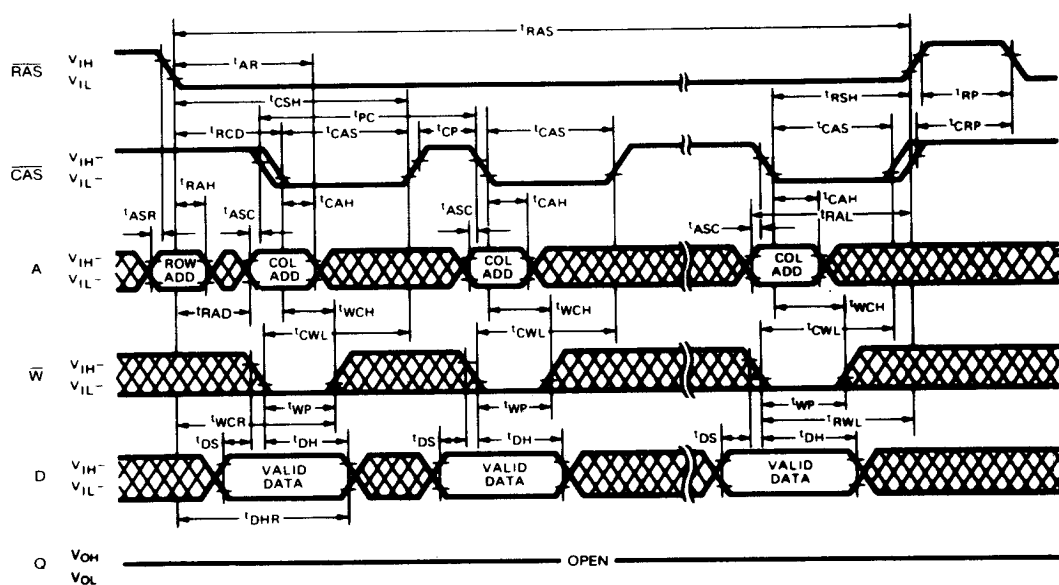
WRITE CYCLE (EARLY WRITE)



FAST PAGE MODE READ CYCLE



FAST PAGE MODE WRITE CYCLE (EARLY WRITE)



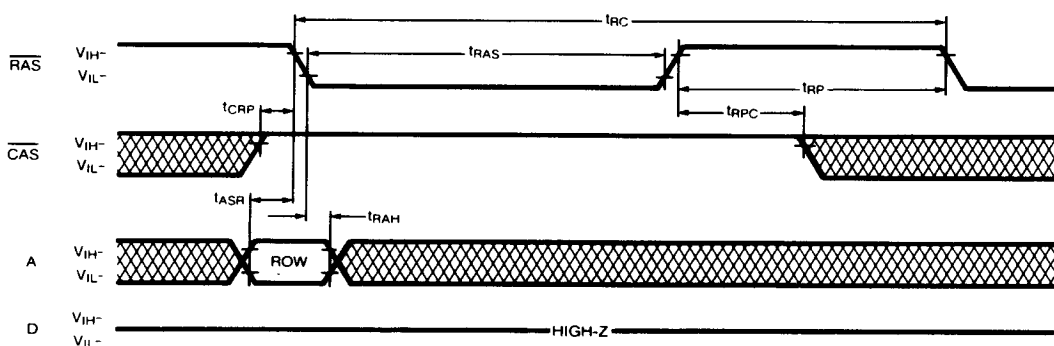
 DON'T CARE

KMM491000/KMM591000 **1M × 9 DRAM SIP and SIMM Memory Modules**

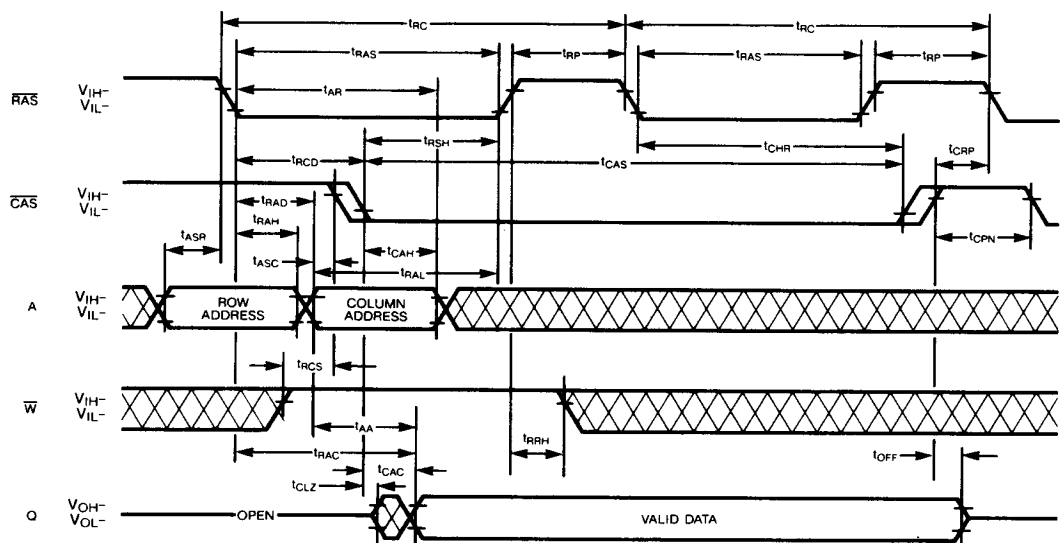
TIMING DIAGRAMS (Continued)

RAS-ONLY REFRESH CYCLE

NOTE: CAS = V_{IH} ; W, D, A_9 = DON'T CARE



HIDDEN REFRESH CYCLE

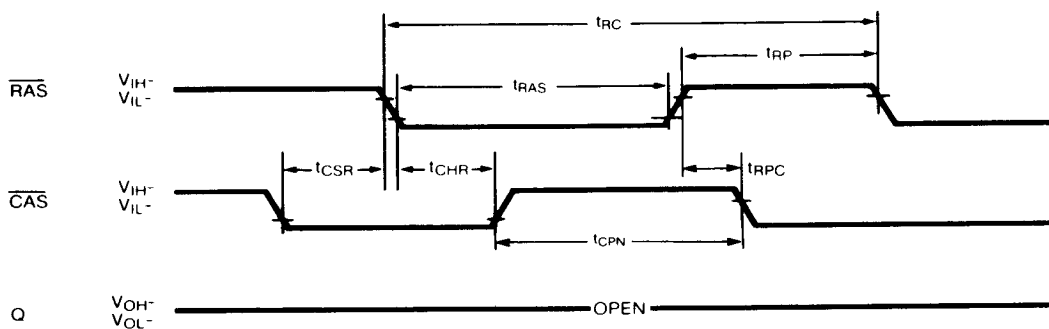


 DON'T CARE

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TIMING DIAGRAMS (Continued)

CAS-BEFORE-RAS REFRESH CYCLE NOTE: Address, \overline{W} , D = DON'T CARE

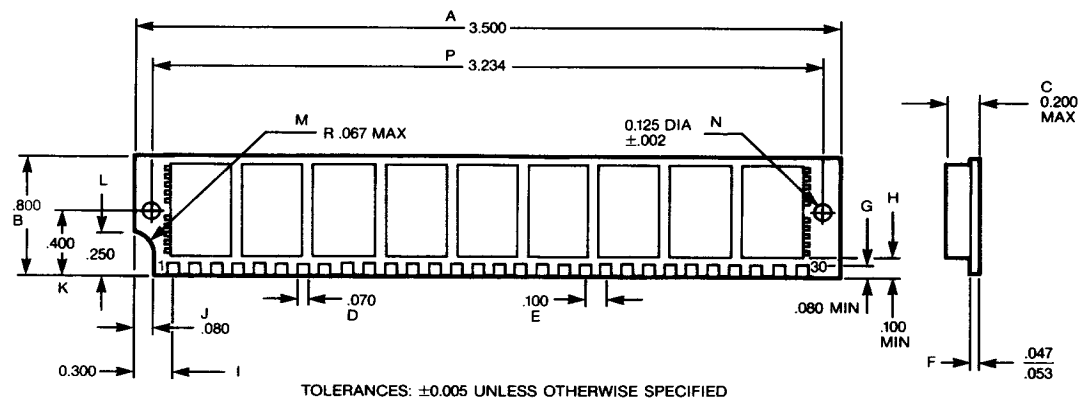


 DON'T CARE

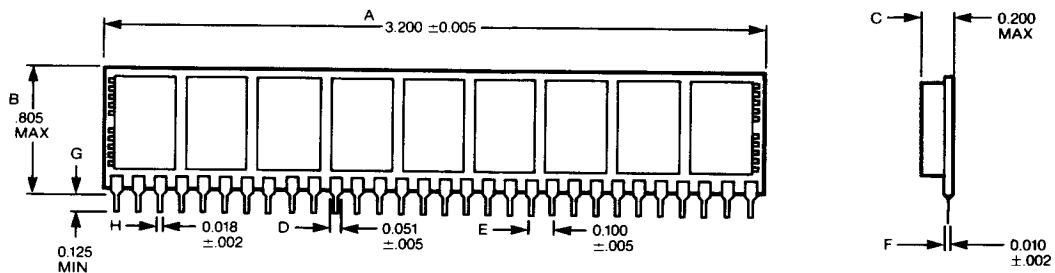
KMM491000/KMM591000 **1M × 9 DRAM SIP and SIMM Memory Modules**

PACKAGE DIMENSIONS

KMM591000 1M × 9 SIMM



KMM491000 1M × 9 SIP



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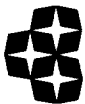
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